



100% Material Declaration Data Sheet VQG44

PK128 (v1.2) September 28, 2006

Material Declaration Data Sheet

Average Weight: 0.4 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.00512	1.28%
	Silicon	7440-21-3	100.00		0.00512	
Die Attach Material					0.00152	0.38%
	Silver	7440-22-4	78.00		0.0011856	
	Epoxy (EP)	Trade Secret	22.00		0.0003344	
Mold Compound					0.26644	66.61%
	Epoxy Resin (EP)	Trade Secret	9.00		0.0239796	
	Phenolic Resin	Trade Secret	7.00		0.0186508	
	Carbon Black	1333-86-4	0.50		0.0013322	
	Silica	60676-86-0	82.50		0.219813	
	Bismuth	7440-69-9	Max 1.00		0.0026644	
Leadframe					0.11692	29.23%
	Copper	7440-50-8	98.85		0.11557542	
	Chromium	7440-47-3	0.30		0.00035076	
	Tin	7440-31-5	0.25		0.0002923	
	Zinc	7440-66-6	0.60		0.00070152	
Leadframe Plating					0.00184	0.46%
	Silver	7440-22-4	100.00		0.00184	
Bond Wire					0.0028	0.70%
	Gold	7440-57-5	100.00		0.0028	
Ext. Plating					0.00536	1.34%
	Tin	7440-31-5	100.00		0.00536	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/20/06	1.0	Initial release.
7/10/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.